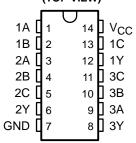
## SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 **TRIPLE 3-INPUT POSITIVE-AND GATES**

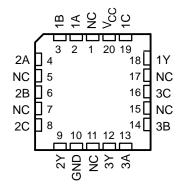
SDAS009D - MARCH 1984 - REVISED NOVEMBER 2002

- 4.5-V to 5.5-V V<sub>CC</sub> Operation
- Max t<sub>pd</sub> of 5.5 ns at 5 V

SN54ALS11A, ... J OR W PACKAGE SN54AS11 . . . J PACKAGE SN74ALS11A, SN74AS11 . . . D, N, OR NS PACKAGE (TOP VIEW)



#### SN54ALS11A, SN54AS11 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### description/ordering information

These devices contain three independent 3-input positive-AND gates. They perform the Boolean functions  $Y = A \bullet B \bullet C$  or  $Y = \overline{\overline{A} + \overline{B} + \overline{C}}$  in positive logic.

#### ORDERING INFORMATION

TA	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74ALS11AN	SN74ALS11AN
	PDIF - N	Tube	SN74AS11N	SN74AS11N
		Tube	SN74ALS11AD	ALS11A
0°C to 70°C	SOIC - D	Tape and reel	SN74ALS11ADR	ALSTIA
0 0 10 70 0	SOIC = D	Tube	SN74AS11D	A C 4 4
		Tape and reel	SN74AS11DR	AS11
	SOP – NS	Tone and real	SN74ALS11ANSR	ALS11A
	30P - NS	Tape and reel	SN74AS11NSR	74AS11
	CDIP – J	Tube	SNJ54ALS11AJ	SNJ54ALS11AJ
	CDIP = 3	Tube	SNJ54AS11J	SNJ54AS11J
–55°C to 125°C	CFP – W	Tube	SNJ54ALS11AW	SNJ54ALS11AW
İ	LCCC – FK	Tube	SNJ54ALS11AFK	SNJ54ALS11AFK
	LCCC - FK	Tube	SNJ54AS11FK	SNJ54AS11FK

<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

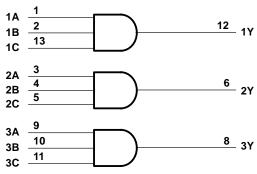
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## FUNCTION TABLE (each gate)

	INPUTS		OUTPUT
Α	В	С	Y
Н	Н	Н	Н
L	X	Χ	L
Х	L	Χ	L
Х	Χ	L	L

### logic diagram, each gate (positive logic)



Pin numbers shown are for the D, J, N, NS, and W packages.

# absolute maximum ratings over operating free-air temperature range (SN54ALS11A, SN74ALS11A) (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>CC</sub>		$\dots \dots \dots \ 7 \ V$
Input voltage, V <sub>I</sub>		7 V
Package thermal impedance, θ <sub>JA</sub> (see Note 1)	: D package	86°C/W
, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	N package	80°C/W
	NS package	76°C/W
Storage temperature range		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 2)

		SN	54ALS1	1A	SN	74ALS1	1A	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V	
VIН	High-level input voltage	2			2			V	
\/··	Low lovel input veltage		0.8‡			0.8			
VIL	Low-level input voltage			0.7§				<b>1</b>	
loh	High-level output current			-0.4			-0.4	mA	
l <sub>OL</sub>	Low-level output current			4			8	mA	
TA	Operating free-air temperature	-55		125	0		70	°C	

<sup>‡</sup> Applies over temperature range –55°C to 70°C

NOTE 2: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>§</sup> Applies over temperature range 70°C to 125°C

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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST O	ONDITIONS	SN	I54ALS1	1A	SN	74ALS11	IA	UNIT
PARAMETER	1531 C	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNII
VIK	V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	,	VCC −2		\	/CC -2		V
\/o:	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OL} = 4 \text{ mA}$		0.25	0.4		0.25	0.4	V
VoL	V <sub>CC</sub> = 4.5 V	$I_{OL} = 8 \text{ mA}$					0.35	0.5	ľ
lį	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 7 V			0.1			0.1	mA
liH	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 2.7 V			20			20	μΑ
I <sub>Ι</sub> Γ	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.4 V			-0.1			-0.1	mA
1 <sub>0</sub> ‡	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
<sup>I</sup> ссн	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 4.5 V		1	1.8		1	1.8	mA
ICCL	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0		1.6	3	·	1.6	3	mA

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

#### switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> SN54A	R <sub>L</sub> = 5 \( = MIN LS11A	TO MAX	§ LS11A	UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A, B, or C	V	2	14	2	13	ns
<sup>t</sup> PHL	A, b, or C	1	2	12.5	2	10	115

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# absolute maximum ratings over operating free-air temperature range (SN54AS11, SN74AS11) (unless otherwise noted)

Supply voltage, V <sub>CC</sub>		7 V
Input voltage, V <sub>I</sub>		7 V
Package thermal impedance, $\theta_{JA}$ (see Note 1):	D package	. 86°C/W
	N package	. 80°C/W
	NS package	. 76°C/W
Storage temperature range	65°C	to 150°C

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



<sup>&</sup>lt;sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

<sup>¶</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11 TRIPLE 3-INPUT POSITIVE-AND GATES

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#### recommended operating conditions (see Note 2)

		S	N54AS1	1	S	N74AS1	1	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vсс	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-2			-2	mA
lOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	DITIONS	SN	54AS11		SN	74AS11		UNIT
PARAMETER	IESI CON	DITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP†	MAX	UNII
V <sub>IK</sub>	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>CC</sub> -2			V <sub>CC</sub> -2			V
$v_{OL}$	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5		0.35	0.5	V
lį	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 7 V			0.1			0.1	mA
lіН	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 2.7 V			20			20	μΑ
IլL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0.4 V			-0.5			-0.5	mA
lO <sup>‡</sup>	V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-30		-112	-30		-112	mA
Iссн	$V_{CC} = 5.5 V,$	V <sub>I</sub> = 4.5 V		4.3	7		4.3	7	mA
<sup>I</sup> CCL	V <sub>CC</sub> = 5.5 V,	V <sub>I</sub> = 0		11.2	18		11.2	18	mA

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

#### switching characteristics (see Figure 1)

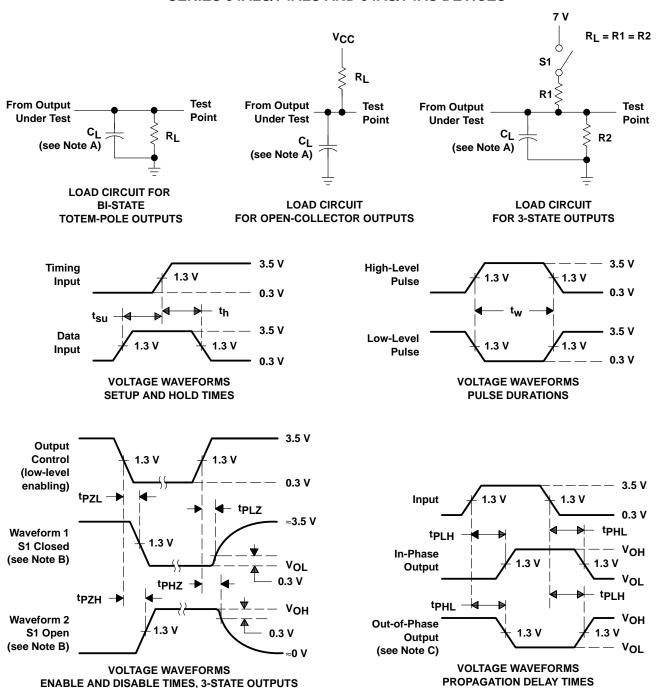
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>C</sub> T <sub>A</sub> SN54		UNIT		
				MIN	MAX	MIN	MAX	
MIN MAX MIN MAX	<sup>t</sup> PLH	A B or C	V	1	6.5	1	6	nc
t <sub>DI H</sub> 1 6.5 1 6	<sup>t</sup> PHL	A, B, 01 C	1	1	6.5	1	5.5	115

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



<sup>&</sup>lt;sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

#### PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics:  $PRR \le 1$  MHz,  $t_r = t_f = 2$  ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-86841012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86841012A SNJ54ALS 11AFK	Samples
5962-8684101CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8684101CA SNJ54ALS11AJ	Samples
5962-8684101DA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8684101DA SNJ54ALS11AW	Samples
5962-9756101QCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9756101QC A SNJ54AS11J	Samples
JM38510/37402BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37402BCA	Samples
M38510/37402BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 37402BCA	Samples
SN54ALS11AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54ALS11AJ	Samples
SN54AS11J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54AS11J	Samples
SN74ALS11ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS11A	Samples
SN74ALS11AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS11AN	Samples
SN74ALS11ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS11A	Samples
SN74AS11D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AS11	Samples
SN74AS11N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74AS11N	Samples
SNJ54ALS11AFK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 86841012A SNJ54ALS 11AFK	Samples
SNJ54ALS11AJ	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8684101CA SNJ54ALS11AJ	Samples



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Orderable Device	Status (1)	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54ALS11AW	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8684101DA SNJ54ALS11AW	Samples
SNJ54AS11J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9756101QC A SNJ54AS11J	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### **PACKAGE OPTION ADDENDUM**

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#### OTHER QUALIFIED VERSIONS OF SN54ALS11A, SN54AS11, SN74ALS11A, SN74AS11:

● Catalog : SN74ALS11A, SN74AS11

• Military : SN54ALS11A, SN54AS11

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS11ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS11ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS11ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ALS11ANSR	SO	NS	14	2000	356.0	356.0	35.0

**PACKAGE MATERIALS INFORMATION** 

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-86841012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8684101DA	W	CFP	14	25	506.98	26.16	6220	NA
SN74ALS11AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74ALS11AN	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS11D	D	SOIC	14	50	506.6	8	3940	4.32
SN74AS11N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AS11N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54ALS11AFK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS11AW	W	CFP	14	25	506.98	26.16	6220	NA

#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
  Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## D (R-PDSO-G14)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



## D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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